

IN THE SPECIFICATION:

Please amend the specification as follows:

FIGS. 1A, 1B and 1C are schematic views FIG. 1 is a schematic view
explaining an example of arrangement relations of constituent elements of a
semiconductor chip according to a first embodiment of the present invention;

FIGS. 2A, 2B, and 2C show examples FIG. 2 shows an example of
lamination of the semiconductor chips according to the first embodiment of the
present invention;

FIG. 3 shows an example of packaging of the semiconductor chips
according to the first embodiment of the present invention;

FIGS. 4A, 4B, and 4C are schematic views FIG. 4 is a schematic view
explaining an example of arrangement relations of the semiconductor chip
according to a second embodiment of the present invention;

FIGS. 5A and 5B are schematic sectional views FIG. 5 is a schematic
sectional view explaining a conversion circuit of the semiconductor chip
according to a second embodiment of the present invention;

FIGS. 6A, 6B, and 6C show examples FIG. 6 shows an example of
lamination of the semiconductor chip according to the second embodiment of the
present invention;

FIG. 7 is a partial enlarged view showing an enlarged area H in FIG. 6;

FIG. 8 shows an example of packaging of the semiconductor chips
according to the second embodiment of the present invention;

FIGS. 9A, 9B and 9C are schematic views FIG. 9 is a schematic view
explaining an example of arrangement relations of the semiconductor chip
according to a third embodiment of the present invention;

FIGS. 10A, 10B, and 10C show examples FIG. 10 shows an example of lamination of the semiconductor chips according to the third embodiment of the present invention;

FIG. 11 shows an example of packaging of the semiconductor chips according to the third embodiment of the present invention;

FIGS. 12A, 12B, and 12C are schematic views FIG. 12 is a schematic view explaining an example of arrangement relations of the semiconductor chip according to a fourth embodiment of the present invention;

FIGS. 13A, 13B, and 13C show examples FIG. 13 shows an example of lamination of the semiconductor chips according to the fourth embodiment of the present invention;

FIG. 14 shows an example of packaging of the semiconductor chips according to the fourth embodiment of the present invention;

FIGS. 15A and 15B are schematic views FIG. 15 is a schematic view explaining an example of arrangement relations of the semiconductor chip according to a fifth embodiment of the present invention;

FIG. 16 shows an example of lamination of the semiconductor chips according to the fifth embodiment of the present invention;

FIGS. 17A and 17B show examples FIG. 17 shows an example of lamination of the semiconductor chips according to the fifth embodiment of the present invention; and

FIG. 18 shows an example of packaging of the semiconductor chips according to the fifth embodiment of the present invention.